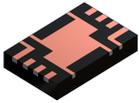


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

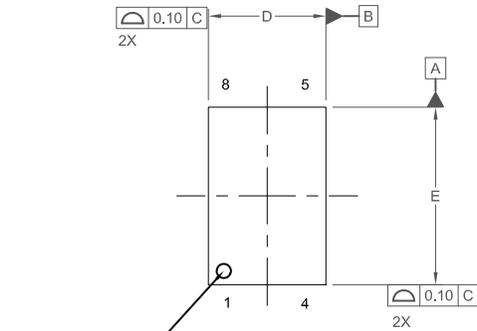


PQFN8 3.30x5.00x0.75, 0.65P

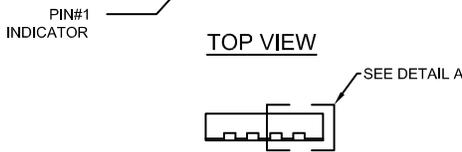
CASE 483AU

ISSUE B

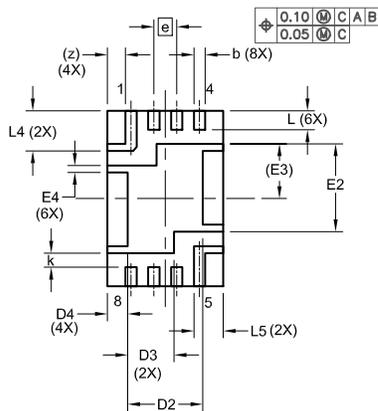
DATE 19 APR 2024



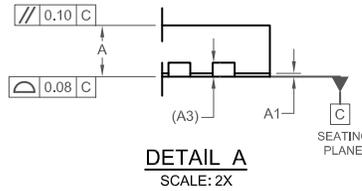
TOP VIEW



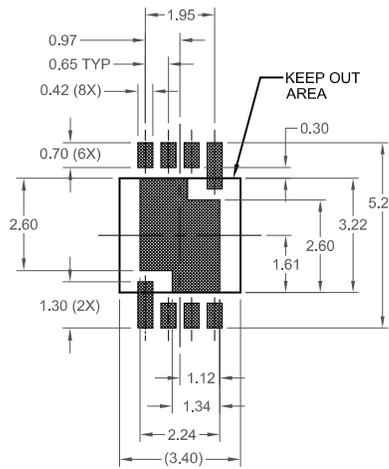
FRONT VIEW



BOTTOM VIEW



DETAIL A
SCALE: 2X



RECOMMENDED LAND PAD

NOTES: UNLESS OTHERWISE SPECIFIED
 A) DOES NOT FULLY CONFORM TO JEDEC REGISTRATION, MO229 DATED 8/2012.
 B) ALL DIMENSIONS ARE IN MILLIMETERS.
 C) DIMENSIONS DO NOT INCLUDE BURRS OR MOLD FLASH. MOLD FLASH OR BURRS DOES NOT EXCEED 0.10MM.
 D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
 E) IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.

| DIM | MILLIMETERS | | |
|-----|-------------|------|------|
| | MIN. | NOM. | MAX. |
| A | 0.70 | 0.75 | 0.80 |
| A1 | 0.00 | - | 0.05 |
| A3 | 0.20 REF | | |
| b | 0.27 | 0.32 | 0.37 |
| D | 3.20 | 3.30 | 3.40 |
| D2 | 2.04 | 2.14 | 2.24 |
| D3 | 1.22 | 1.32 | 1.42 |
| D4 | 0.48 | 0.58 | 0.68 |
| E | 4.90 | 5.00 | 5.10 |
| E2 | 2.40 | 2.50 | 2.60 |
| E3 | 1.56 REF | | |
| E4 | 0.10 | 0.20 | 0.30 |
| e | 0.65 BSC | | |
| k | 0.30 | 0.40 | 0.50 |
| L | 0.44 | 0.54 | 0.64 |
| L4 | 1.04 | 1.14 | 1.24 |
| L5 | 0.75 | 0.85 | 0.95 |
| z | 0.51 REF | | |

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

| | | |
|------------------|-----------------------------|--|
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| DESCRIPTION: | PQFN8 3.30x5.00x0.75, 0.65P | PAGE 1 OF 1 |

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